

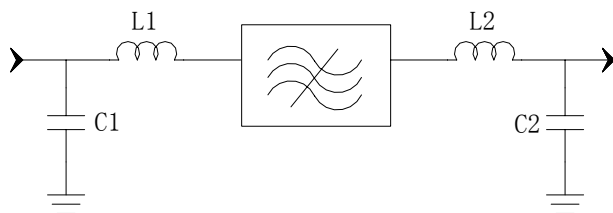
Specifications

Parameter	Unit	Minimum	Typical	Maximum
Center Frequency	MHz	139.9	140	140.1
Insertion Loss	dB		27.8	29.3
1.5 dB Bandwidth	MHz	14.38	14.4	
25 dB Bandwidth	MHz		15.35	15.4
30 dB Bandwidth	MHz		15.5	16
40 dB Bandwidth	MHz		16.34	16.7
Group delay Variation($f_0 \pm 7.2\text{MHz}$)	nsec		107	130
Phase Linearity($f_0 \pm 7.2\text{MHz}$)	degree		10	15
Passband Variation	dB		1	1.5
Absolute Delay	usec		2.26	2.3
Ultimate Rejection	dB	35	40	
Substrate Material		112LT		
Ambient Temperature	°C	25		
Package Size	DIP2712 (27.2x12.7x5.2mm ³)			

Notes:

1. All specifications are based on the test circuit shown
2. In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temperature
3. Electrical margin has been built into the design to account for the variations due to temperature drift and manufacturing tolerances
4. This is the optimum impedance in order to achieve the performance show

Matching Configuration




L1=18nH L2=56nH

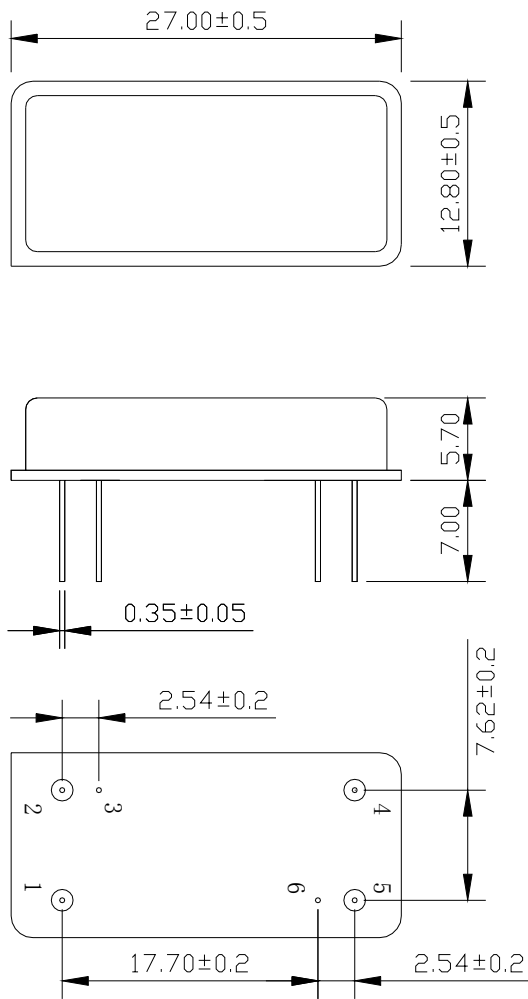
C1=51pF C2=33pF


Source/Load Impedance=50 ohm

Notes - Component values may change depending on board layout.

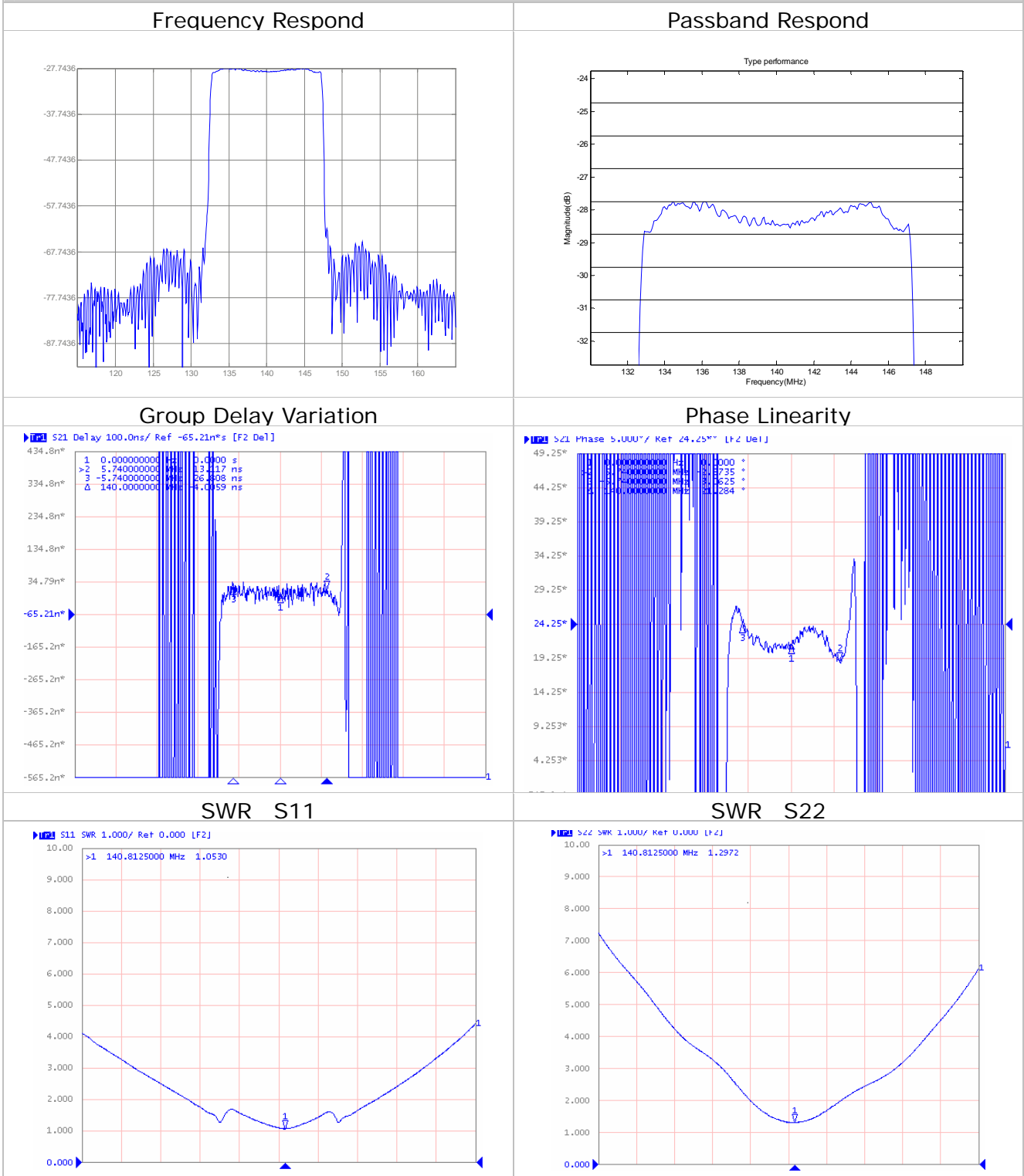
	SIPAT Co., Ltd. (CETC No. 26 Research Institute) Nanping Huayuan Road No. 14 Chongqing, China, 400060	Part Number	LBT14066	
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Package Dimension



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Typical Performance



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